



N-Channel 2.5-V (G-S) MOSFET

CHARACTERISTICS

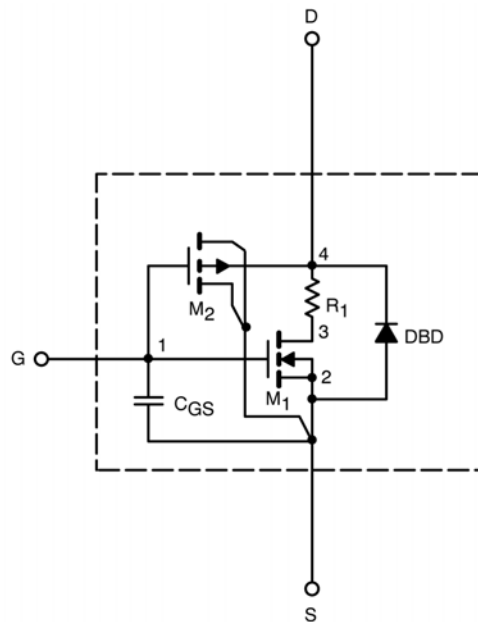
- N-Channel Vertical DMOS
- Macro Model (Subcircuit Model)
- Level 3 MOS
- Apply for both Linear and Switching Application
- Accurate over the -55 to 125°C Temperature Range
- Model the Gate Charge, Transient, and Diode Reverse Recovery Characteristics

DESCRIPTION

The attached spice model describes the typical electrical characteristics of the n-channel vertical DMOS. The subcircuit model is extracted and optimized over the -55 to 125°C temperature ranges under the pulsed 0-V to 5-V gate drive. The saturated output impedance is best fit at the gate bias near the threshold voltage.

A novel gate-to-drain feedback capacitance network is used to model the gate charge characteristics while avoiding convergence difficulties of the switched C_{gd} model. All model parameter values are optimized to provide a best fit to the measured electrical data and are not intended as an exact physical interpretation of the device.

SUBCIRCUIT MODEL SCHEMATIC



This document is intended as a SPICE modeling guideline and does not constitute a commercial product data sheet. Designers should refer to the appropriate data sheet of the same number for guaranteed specification limits.



SPECIFICATIONS (T _J = 25°C UNLESS OTHERWISE NOTED)				
Parameter	Symbol	Test Condition	Typical	Unit
Static				
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	0.75	V
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 4.5 V	624	A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 4.5 V, I _D = 13.2 A	0.007	Ω
		V _{GS} = 2.5 V, I _D = 11 A	0.0086	
Forward Transconductance ^a	g _{fs}	V _{DS} = 10 V, I _D = 13.2 A	68	S
Diode Forward Voltage ^a	V _{SD}	I _S = 2.3 A, V _{GS} = 0 V	0.81	V
Dynamic				
Total Gate Charge ^b	Q _g	V _{DS} = 10 V, V _{GS} = 4.5 V, I _D = 13.2 A	50	nC
Gate-Source Charge ^b	Q _{gs}		13	
Gate-Drain Charge ^b	Q _{gd}		10	
Turn-On Delay Time ^{b, c}	t _{d(on)}	V _{DD} = 10 V, R _L = 10 Ω I _D ≅ 1 A, V _{GEN} = 4.5 V, R _G = 6 Ω	40	ns
Rise Time ^{b, c}	t _r		46	
Turn-Off Delay Time ^{b, c}	t _{d(off)}		210	
Fall Time ^{b, c}	t _f		55	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.3 A, di/dt = 100 A/μs	55	

Notes

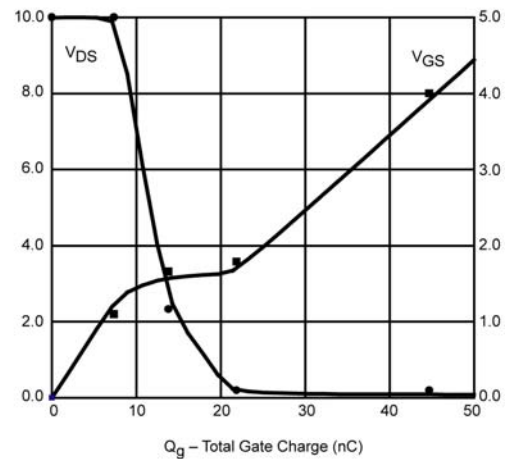
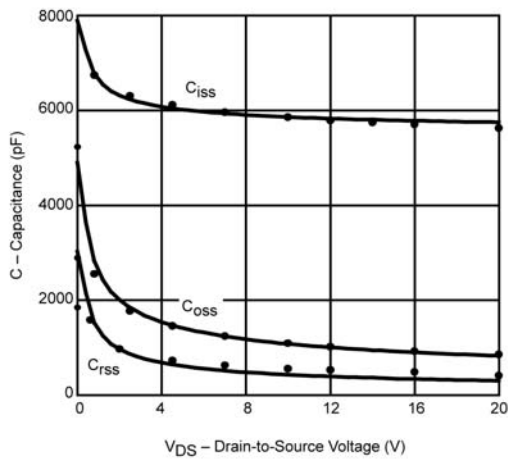
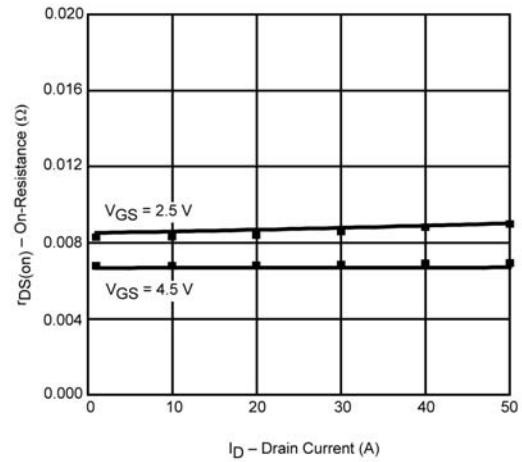
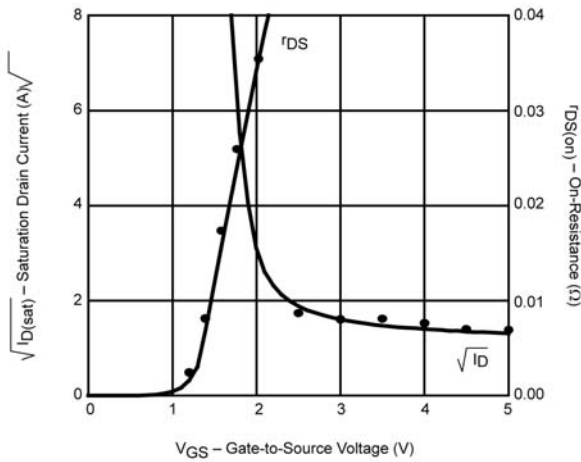
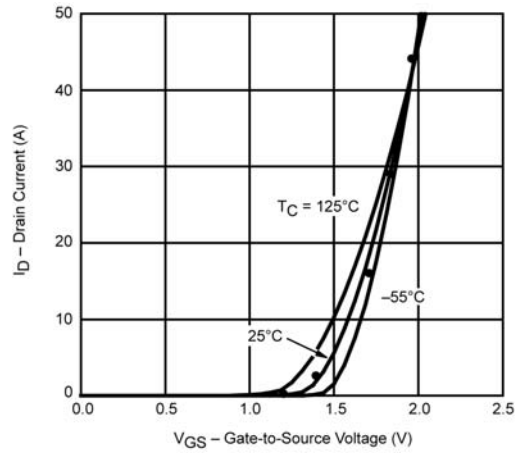
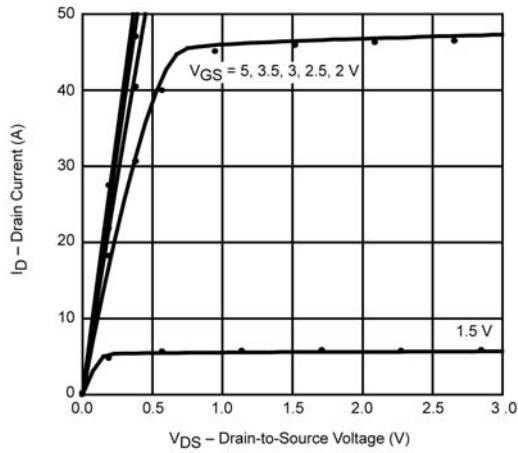
- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%
- b. Independent of operating temperature
- c. Include only parasitic components presented in the model circuit.



SPICE Device Model Si4466DY

Vishay Siliconix

COMPARISON OF MODEL WITH MEASURED DATA ($T_J=25^\circ\text{C}$ UNLESS OTHERWISE NOTED)



Note: Dots and squares represent measured data.



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